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Case Study

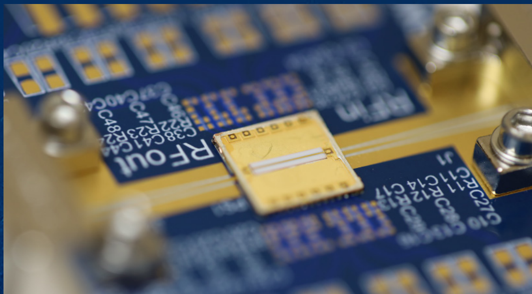
PolyStrata Package's Measured Success Against Ceramic Alternatives

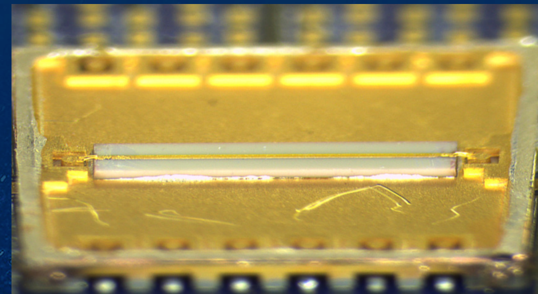
Nuvotronics recently performed a comparison focusing on the performance of PolyStrata® RF packaging technology versus traditional ceramic alternatives.

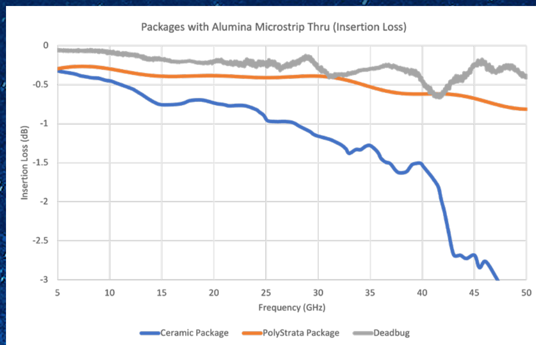
The results demonstrate that PolyStrata RF packaging outperforms ceramic alternatives, making it a promising and cost-effective solution for next-generation RF applications.

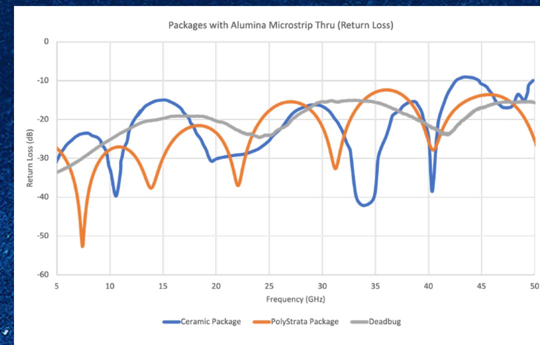
Test Setup:

- A 5mm Alumina microstrip thru-line is mounted in a PolyStrata package, which is then soldered to a printed circuit board (PCB).
- Results from a similar test using a traditional ceramic package with an embedded thru-line mounted to a PCB.









Deadbug Measurements:
Deadbug measurements are taken by directly probing the package prior to assembly to the PCB. The package is flipped upside down with the leads acing up. This helps isolate the performance of the package itself without PCB effects.

Key Takeaways:

- **Measured success:** PolyStrata Package shows superior or competitive performance compared to ceramic alternatives.
- **Packaging improvement:** PolyStrata Package advanced design and materials result in better RF characteristics, lower losses and enhanced signal integrity.
- **PolyStrata RF Packaging** is a next-generation RF (radio frequency) packaging solution that offers measured improvements in electrical performance while being a cost-competitive option.